

TOSHIBA DIODE SILICON EPITAXIAL PLANAR TYPE

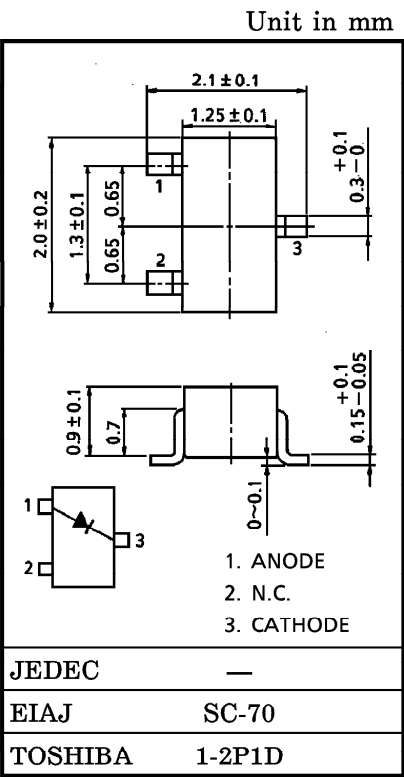
1SS370

HIGH VOLTAGE, HIGH SPEED SWITCHING APPLICATIONS

- Low Forward Voltage : $V_F(2)=0.9V$ (TYP.)
- Fast Reverse Recovery Time : $t_{rr}=60ns$ (MAX.)
- Small Total Capacitance : $C_T=1.5pF$ (TYP.)
- Small Package : SC-70

MAXIMUM RATING ($T_a=25^{\circ}C$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Maximum (Peak) Reverse Voltage	V_{RM}	250	V
Reverse Voltage	V_R	200	V
Maximum (Peak) Forward Current	I_{FM}	300	mA
Average Forward Current	I_O	100	mA
Surge Current (10ms)	I_{FSM}	2	A
Power Dissipation	P	100	mW
Junction Temperature	T_j	125	$^{\circ}C$
Storage Temperature Range	T_{stg}	$-55\sim125$	$^{\circ}C$



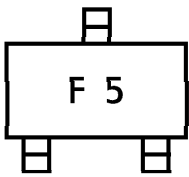
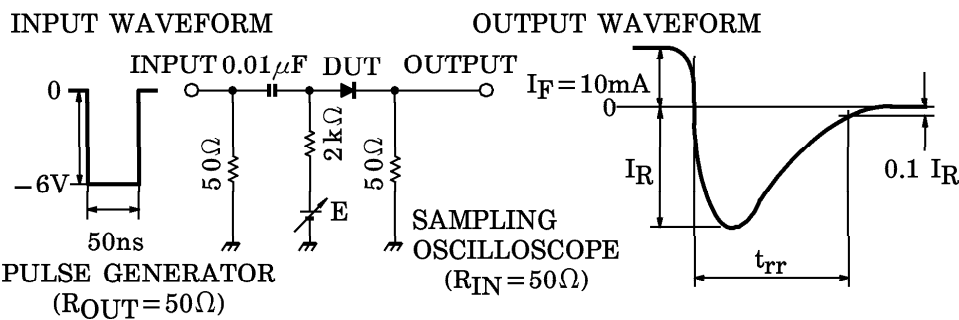
ELECTRICAL CHARACTERISTICS ($T_a=25^{\circ}C$)

Weight : 0.006g

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_F(1)$	$I_F=10mA$	—	0.72	1.0	V
	$V_F(2)$	$I_F=100mA$	—	0.90	1.2	
Reverse Current	$I_R(1)$	$V_R=50V$	—	—	0.1	μA
	$I_R(2)$	$V_R=200V$	—	—	1.0	
Total Capacitance	C_T	$V_R=0, f=1MHz$	—	1.5	3.0	pF
Reverse Recovery Time	t_{rr}	$I_F=10mA$, Fig.1	—	10	60	ns

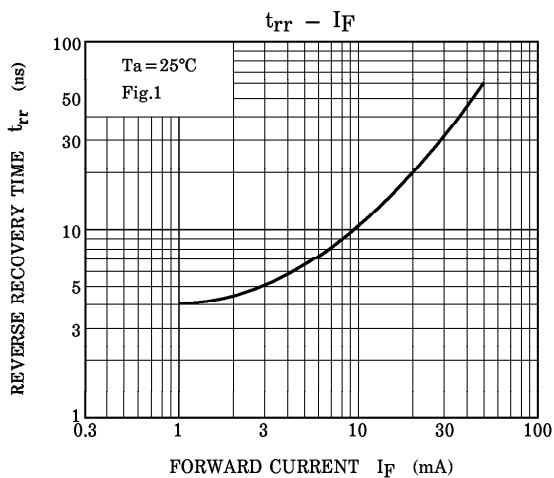
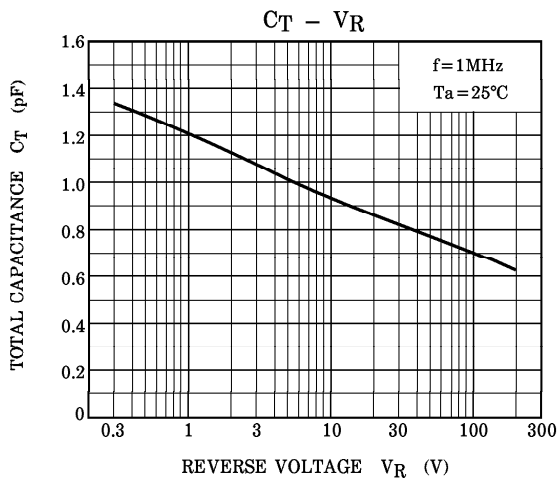
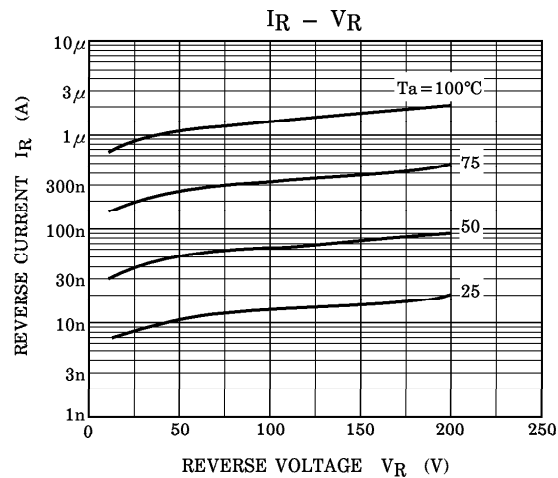
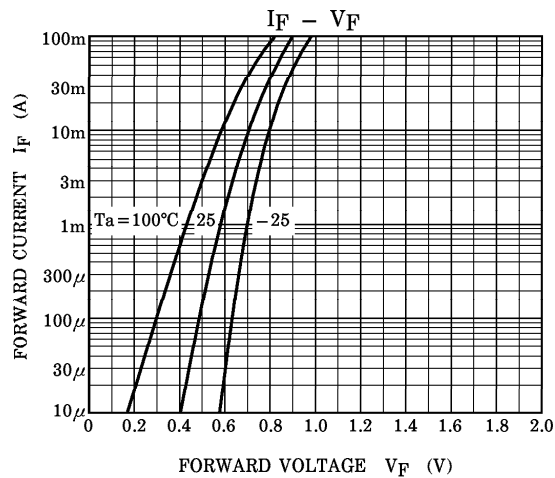
Fig.1 : REVERSE RECOVERY TIME (t_{rr}) TEST CIRCUIT

MARKING



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